

## U.S. PATENT DOCUMENTS

[illegible]

## FOREIGN PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS								
		Document Number	Date of Publication	Country	Class	SubClass	Translation	
							Yes	No
Lt		WO 99/30362	6/17/99	PCT				
Lt		WO 92/18600	10/29/92	PCT				
Lt		0 969 058 A2	1/5/00	EPO				
	/			/				

**OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)**

LT			International Search Report for PCT/US01/02385
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**EXAMINER**

Luan Thai

**Date Considered**

9/2002

**\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.**

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<b>INFORMATION DISCLOSURE STATEMENT</b>		Atty. Docket No.: 53434USA8C.009		Serial No.: 09/690,600		
		Applicant(s): Peter B. Hogerton et al.				
		Filing Date: October 17, 2000		Group: 3729		
<b>U.S. PATENT DOCUMENTS</b>						
Examiner Initial	Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
LT	5,068,714	11/26/91	Seipler	357	80	
LT	5,128,746	7/7/92	Pennisi et al.	357	72	
LT	5,543,585	8/6/96	Booth et al.	174	261	
<b>FOREIGN PATENT DOCUMENTS</b>						
	Document Number	Date of Publication	Country	Class	SubClass	Translation
						Yes No
LT	0 332 402 A2	9/13/89	EPO			
	0 560 072 A2	9/15/93	EPO			
	0 099 544	7/13/83	EPO			
	HEI 2[1990]-23623	1/25/90	Japanese Kokai			x
	HEI 1[1989]-164041	6/28/89	Japanese Kokai			x
	HEI 4[1992]-304640	10/28/92	Japanese Kokai			x
LT	SHO 61[1986]-30059	2/12/86	Japanese Kokai			x
<b>OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)</b>						
LT	S. Shi et al., "High Performance Underfills for Low-Cost Flip-chip Applications", 1997 Int'l Symposium on Adv. Packaging Materials, March 1997, pp. 42-45					
	Gamota et al., "Advanced Flip Chip Materials: Reflowable Underfill Systems", EEP Vol. 19, Advances in Electronic Packaging - 1997 Vol. 1 ASME 1997, pp. 365-371					
	Johnson et al., "Reflow-Curable Polymer Fluxes for Flip Chip Assembly", Proc. Surface Mount Int' 1997, pp. 267-272					
	Gilleo, Ken, "Direct Chip Interconnect Using Polymer Bonding", 1989 Proceedings 39 <sup>th</sup> Electronic Components Conf., May 22-24 1989, pages 37-44					
	"Direct Chip Bonding Using Transferred Conductive Adhesive Film", IBM Technical Disclosure Bulletin, Vol. 32, No. 10B, March, 1990, pgs. 474-475					
	Ostmann et al., "Implementation of a Chemical Wafer Bumping Process", 1995 IEPS Conference, pp. 354-366					
	Kloeser et al., "Approaches to Flip Chip Technology Using Electroless Nickel - Gold Bumps", 1995 Japan IEMT Symposium, pp. 60-66					
LT	Kloeser et al., "Low Cost Flip Chip Technologies Based on Chemical Nickel Bumping and Solder Printing", International Journal of Microcircuits and Electronic packaging, Vol. 20, No. 3, pp 383-390					
<b>EXAMINER</b>  Luan Thai			<b>Date Considered</b>  3/2002			

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